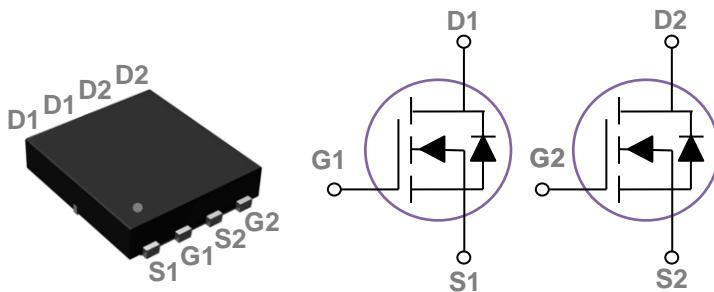


General Description

These N-Channel enhancement mode power field effect transistors are using trench DMOS technology. This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for high efficiency fast switching applications.

PPAK5x6 Dual Pin Configuration



BVDSS	RDS(ON)	ID
100V	330mΩ	6.6A

Features

- 100V, 6.6A, RDS(ON) = 330mΩ@VGS = 10V
- Improved dv/dt capability
- Fast switching
- 100% EAS Guaranteed
- Green Device Available

Applications

- Networking
- Load Switch
- LED applications

Absolute Maximum Ratings $T_c=25^\circ\text{C}$ unless otherwise noted

Symbol	Parameter	Rating	Units
V _{DS}	Drain-Source Voltage	100	V
V _{Gs}	Gate-Source Voltage	±20	V
I _D	Drain Current – Continuous ($T_c=25^\circ\text{C}$)	6.6	A
	Drain Current – Continuous ($T_c=100^\circ\text{C}$)	4.2	A
I _{DM}	Drain Current – Pulsed ¹	26.4	A
P _D	Power Dissipation ($T_c=25^\circ\text{C}$)	32.2	W
	Power Dissipation – Derate above 25°C	0.26	W/°C
T _{STG}	Storage Temperature Range	-55 to 150	°C
T _J	Operating Junction Temperature Range	-55 to 150	°C

Thermal Characteristics

Symbol	Parameter	Typ.	Max.	Unit
R _{θJA}	Thermal Resistance Junction to ambient	---	62	°C/W
R _{θJC}	Thermal Resistance Junction to Case	---	3.88	°C/W



100V Dual N-Channel MOSFETs

PDC0854T

Electrical Characteristics ($T_J=25\text{ }^{\circ}\text{C}$, unless otherwise noted)**Off Characteristics**

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
BV_{DSS}	Drain-Source Breakdown Voltage	$V_{GS}=0\text{V}$, $I_D=250\mu\text{A}$	100	---	---	V
$\Delta BV_{DSS}/\Delta T_J$	BV_{DSS} Temperature Coefficient	Reference to $25\text{ }^{\circ}\text{C}$, $I_D=1\text{mA}$	---	0.09	---	V/C
I_{DS}	Drain-Source Leakage Current	$V_{DS}=100\text{V}$, $V_{GS}=0\text{V}$, $T_J=25\text{ }^{\circ}\text{C}$	---	---	1	μA
		$V_{DS}=80\text{V}$, $V_{GS}=0\text{V}$, $T_J=125\text{ }^{\circ}\text{C}$	---	---	10	μA
I_{GS}	Gate-Source Leakage Current	$V_{GS}=\pm 20\text{V}$, $V_{DS}=0\text{V}$	---	---	± 100	nA

On Characteristics

$R_{DS(ON)}$	Static Drain-Source On-Resistance ²	$V_{GS}=10\text{V}$, $I_D=3\text{A}$	---	270	330	$\text{m}\Omega$
		$V_{GS}=4.5\text{V}$, $I_D=2\text{A}$	---	280	340	$\text{m}\Omega$
$V_{GS(th)}$	Gate Threshold Voltage	$V_{GS}=V_{DS}$, $I_D=250\mu\text{A}$	1.2	1.8	2.5	V
			---	-5	---	mV/C
g_{fs}	Forward Transconductance	$V_{DS}=10\text{V}$, $I_D=1\text{A}$	---	2.3	---	S

Dynamic Characteristics

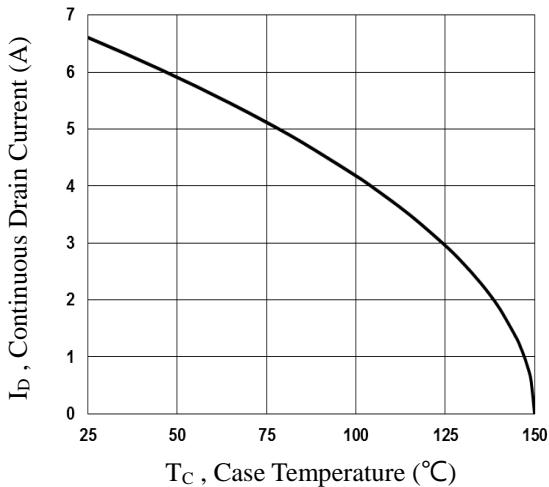
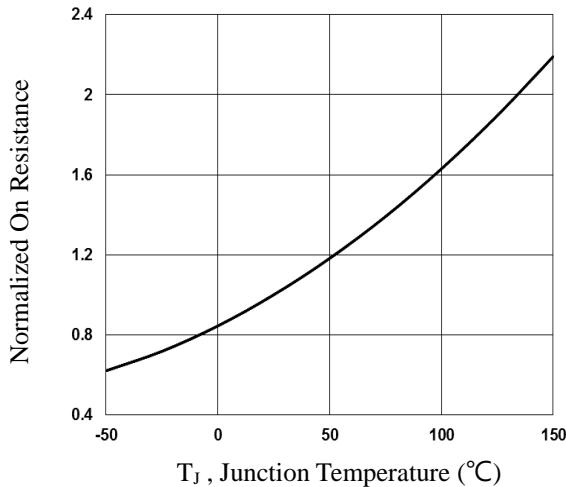
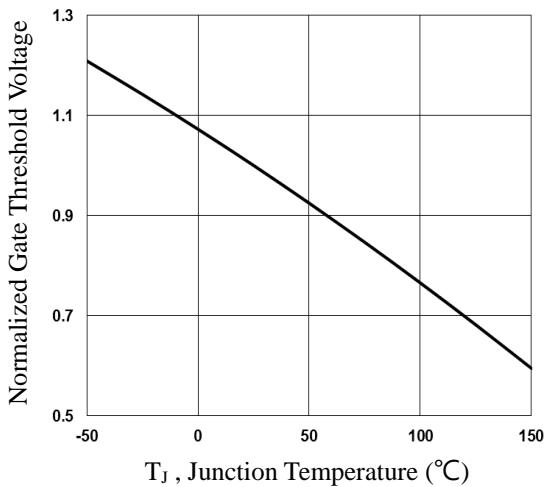
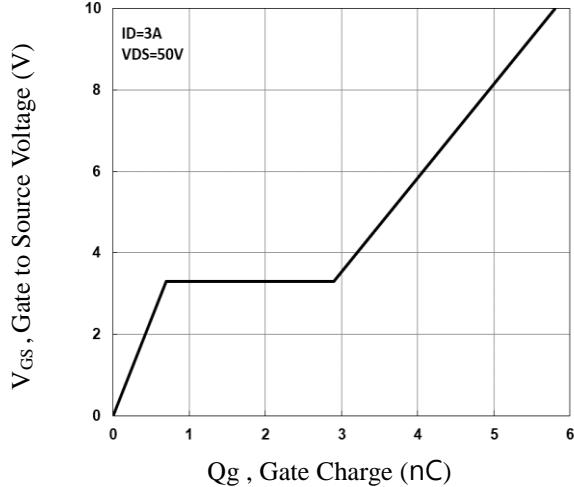
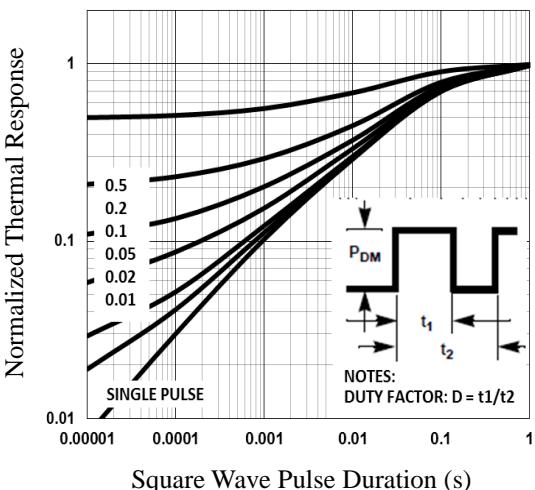
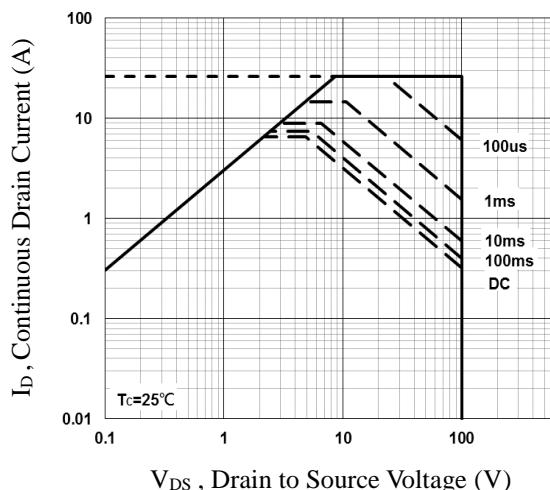
Q_g	Total Gate Charge ^{2,3}	$V_{DS}=50\text{V}$, $V_{GS}=4.5\text{V}$, $I_D=3\text{A}$	---	3.5	6	nC	
			---	5.8	10		
Q_{gs}	Gate-Source Charge ^{2,3}	$V_{DS}=50\text{V}$, $V_{GS}=10\text{V}$, $I_D=3\text{A}$	---	0.7	3		
			---	2.2	5		
			---	4	6	ns	
			---	3	5		
$T_{d(on)}$	Turn-On Delay Time ^{2,3}	$V_{DD}=50\text{V}$, $V_{GS}=10\text{V}$, $R_G=6\Omega$ $I_D=3\text{A}$	---	6	10	ns	
			---	6	10		
T_r	Rise Time ^{2,3}		---	5	8		
			---	5	8		
C_{iss}	Input Capacitance	$V_{DS}=50\text{V}$, $V_{GS}=0\text{V}$, $F=1\text{MHz}$	---	470	705	pF	
			---	12	18		
			---	8	12		
R_g	Gate resistance	$V_{GS}=0\text{V}$, $V_{DS}=0\text{V}$, $F=1\text{MHz}$	---	2.8	---	Ω	

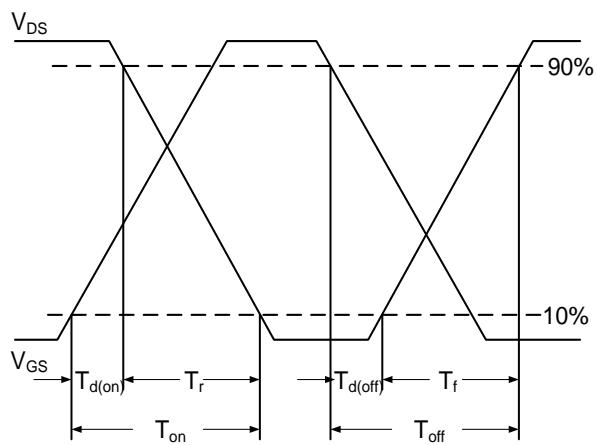
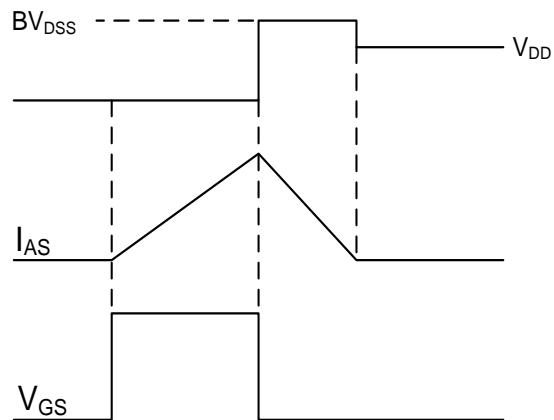
Drain-Source Diode Characteristics

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
I_s	Continuous Source Current	$V_G=V_D=0\text{V}$, Force Current	---	---	6.6	A
			---	---	13.2	A
V_{SD}	Diode Forward Voltage ²	$V_{GS}=0\text{V}$, $I_s=1\text{A}$, $T_J=25\text{ }^{\circ}\text{C}$	---	---	1	V
			---	35	---	ns
Q_{rr}	Reverse Recovery Charge	$V_R=100\text{V}$, $I_s=3\text{A}$ $di/dt=100\text{A}/\mu\text{s}$, $T_J=25\text{ }^{\circ}\text{C}$	---	30	---	nC
			---	30	---	nC

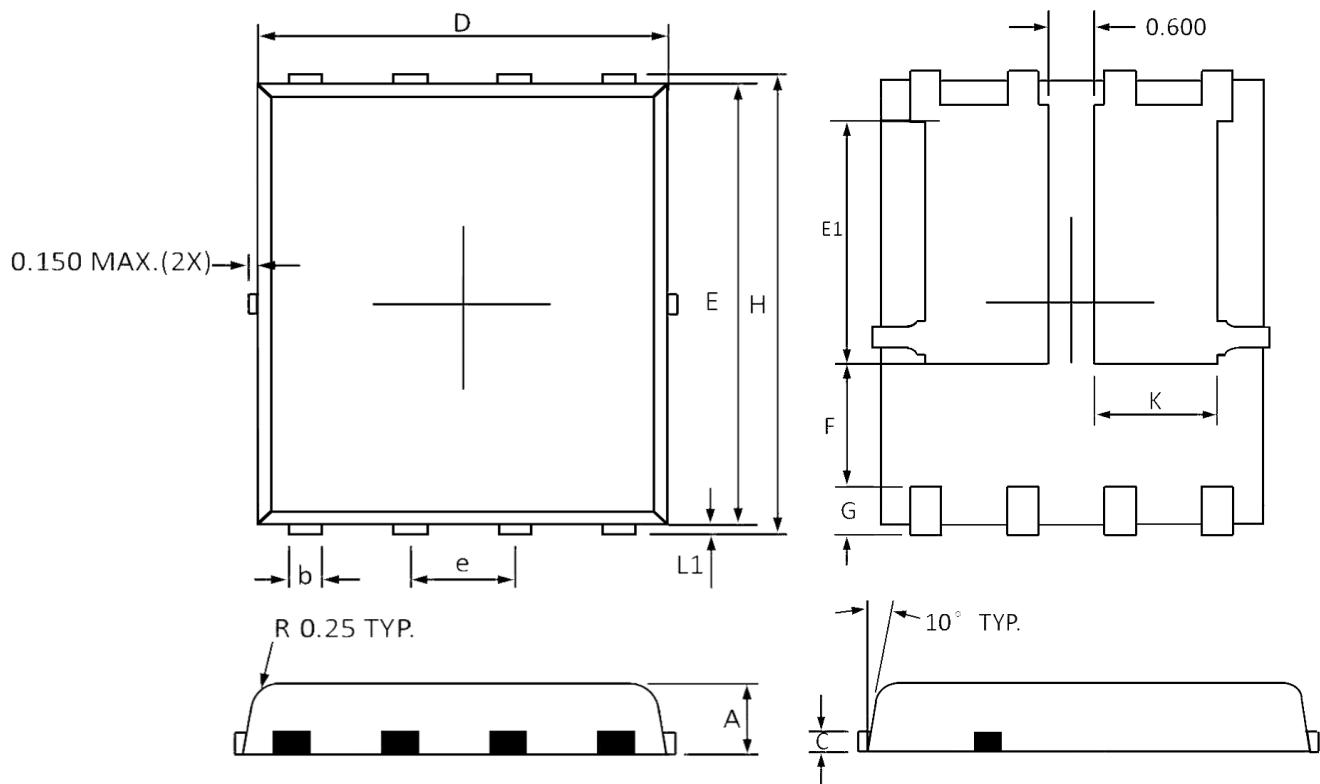
Note :

1. Repetitive Rating : Pulsed width limited by maximum junction temperature.
2. The data tested by pulsed , pulse width $\leq 300\mu\text{s}$, duty cycle $\leq 2\%$.
3. Essentially independent of operating temperature.


Fig.1 Continuous Drain Current vs. TC

Fig.2 Normalized RDSON vs. TJ

Fig.3 Normalized Vth vs. TJ

Fig.4 Gate Charge Waveform

Fig.5 Normalized Transient Impedance

Fig.6 Maximum Safe Operation Area


Fig.7 Switching Time Waveform

Fig.8 EAS Waveform

PPAK5x6 Dual PACKAGE INFORMATION



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	0.800	1.200	0.031	0.047
b	0.300	0.510	0.012	0.020
C	0.250 Ref		0.010 Ref	
D	4.800	5.400	0.189	0.213
E	5.450	5.960	0.215	0.235
E1	3.200	3.800	0.126	0.150
e	1.27 BSC		0.050 BSC	
F	1.000	1.900	0.039	0.075
G	0.380	0.800	0.015	0.031
H	5.850	6.300	0.230	0.248
L1	0.050	0.250	0.002	0.010
K	1.500	1.900	0.059	0.074

PPAK5X6 Dual RECOMMENDED LAND PATTERN